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**Mechanical Data** 

Case: SOT-563

HIGH VOLTAGE DUAL SWITCHING DIODE

Case Material: Molded Plastic, "Green" Molding Compound.

Terminals: Finish - Matte Tin annealed over Copper leadframe.

**BAW101V** 

#### Features

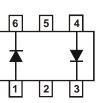
- Fast Switching Speed: Maximum of 50ns
- High Reverse Breakdown Voltage: 325V for Single Diode or 650V for Series Connection
- Two Electrically Isolated Elements in a Single Compact Package
- Low Leakage Current: Maximum of 50nA when V<sub>R</sub> = 5V or Maximum of 150nA when V<sub>R</sub> = 250V at Room Temperature
   Thermally Efficient Copper Alloy leadframe for High Power
- Thermany Encient Copper Alloy leadname for High Power Dissipation
- Lead, Halogen and Antimony Free, RoHS Compliant (Note 3)
- "Green" Device (Note 4)



Top View



Bottom View



UL Flammability Classification Rating 94V-0

Moisture Sensitivity: Level 1 per J-STD-020

Solderable per MIL-STD-202, Method 208

Marking Information: See Page 2

Ordering Information: See Page 2

Weight: 0.006 grams (approximate)

**Device Schematic** 

#### **Maximum Ratings** $@T_A = 25^{\circ}C$ unless otherwise specified

Characteristi	Symbol	Value	Unit	
Repetitive Peak Reverse Voltage	Single Diode	N/	325	V
Repetitive Feak Reverse voltage	Series Connection	V <sub>RRM</sub>	650	v
Working Peak Reverse Voltage	Single Diode	V <sub>RWM</sub>	325	N/
DC Blocking Voltage	Series Connection	V <sub>R</sub>	650	v
RMS Reverse Voltage		V <sub>R(RMS)</sub>	230	V
Forward Current (Note 2) Single Diode Loaded Double Diode Loaded		IF	250 140	mA
Non-Repetitive Peak Forward Surge Curre		I <sub>FSM</sub>	8.0	A
Repetitive Peak Forward Current @ t = 8.3	Bms (Note 2)	I <sub>FRM</sub>	3.0	A

# **Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 2)	PD	500	mW
Thermal Resistance Junction to Ambient Air (Note 2)	R <sub>0JA</sub>	250	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C

## Electrical Characteristics @T<sub>A</sub> = 25°C unless otherwise specified

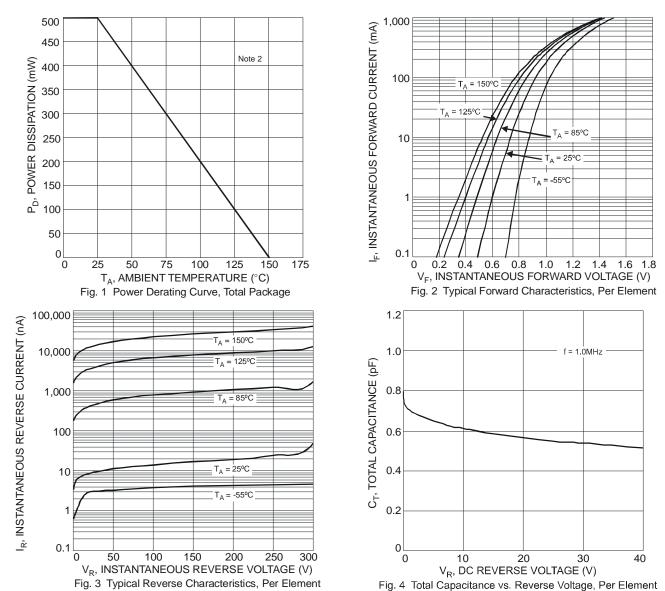
Characteristic		Min	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 1)	V <sub>(BR)R</sub>	300	—	V	I <sub>R</sub> = 100μA
Forward Voltage	VF	_	1.1	V	I <sub>F</sub> = 100mA
Reverse Current (Note 1)	I <sub>R</sub>		50 150 50	nA nA μA	V <sub>R</sub> = 5V V <sub>R</sub> = 250V V <sub>R</sub> = 250V, T <sub>J</sub> = 150°C
Total Capacitance	CT	_	2.0	pF	V <sub>R</sub> = 0, f = 1.0MHz
Reverse Recovery Time		_	50	ns	$I_F = I_R = 30 \text{mA},$ $I_{rr} = 0.1 \times I_R, R_L = 100\Omega$

Notes: 1. Short duration pulse test used to minimize self-heating effect.

2. Part mounted on FR-4 board with recommended pad layout, which can be found on our website at http://www.diodes.com/datasheets/ap02001.pdf.

No purposefully added lead. Halogen and Antimony Free.
 Diodes Inc.'s "Green" policy can be found on our website at http://www.diodes.com/products/lead\_free/index.php.





### Ordering Information (Notes 5 & 6)

Part Number	Case	Packaging
BAW101V-7	SOT-563	3000/Tape & Reel

 Notes:
 5. For packaging details, go to our website at http://www.diodes.com/datasheets/ap02007.pdf.

 6. Package is non-polarized. Parts may be on reel in orientation illustrated, 180° rotated, or mixed (both ways).

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### **Marking Information**

Year         2010         2011         2012         2013         2014         2015         2016           Code         X         Y         Z         A         B         C         D	Date Code Key	К95	YM OR	К95 YM WA S6X	YM = Date Y = Year (	duct Type Marking Code Marking ex: X = 2010) n (ex: 9 = Septemt	-	
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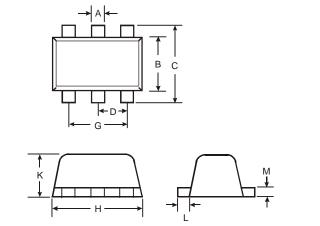
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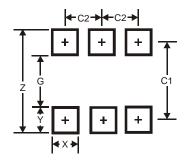


# **Package Outline Dimensions**



SOT-563						
Dim	Min	Max	Тур			
Α	0.15	0.30	0.20			
в	1.10	1.25	1.20			
С	1.55	1.70	1.60			
D	-	-	0.50			
G	0.90	1.10	1.00			
Н	1.50	1.70	1.60			
Κ	0.55	0.60	0.60			
L	0.10	0.30	0.20			
Μ	0.10	0.18	0.11			
All Dimensions in mm						

# Suggested Pad Layout



Dimensions	Value (in mm)
Z	2.2
G	1.2
Х	0.375
Y	0.5
C1	1.7
C2	0.5



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